

Title (en)

COUPLING ELEMENT FOR A HF STRIPLINE STRUCTURE

Title (de)

KOPPELEMENT FÜR EINE HF-STREIFENLEITERSTRUKTUR

Title (fr)

ELEMENT DE COUPLAGE POUR UNE STRUCTURE EN LIGNE TRIPLAQUE HF

Publication

**EP 1428288 B1 20081008 (DE)**

Application

**EP 02742718 A 20020507**

Priority

- DE 0201639 W 20020507
- DE 10134685 A 20010720

Abstract (en)

[origin: DE10134685A1] The coupling element is a meander-shaped finger coupling structure in the form of a thin film structure on a silicon bearer contacted by the strip conducting tracks of the HF strip conductor structure by metalization. The metalization of the strip conducting tracks is in the form of distance holders that guarantee a defined air gap between the silicon bearer and HF substrate, especially when applying the bearer to the strip conducting tracks. The coupling element consists of a finger coupling structure in the form of a thin film structure (6) on a silicon bearer (7) contacted by the strip conducting tracks of the high frequency strip conductor structure (4) by metalization. The finger coupling structure is meander-shaped and the metalization of the strip conducting tracks is in the form of distance holders (9) that guarantee a defined air gap between the silicon bearer and an HF substrate (5), especially when applying the silicon bearer to the strip conducting tracks.

IPC 8 full level

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